



Material Content Data Sheet



Sales Product Name		IPP100N08S2-07		Issued		31. July 2018		
MA#		MA000275850						
Package		PG-TO220-3-1		Weight*		2040.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.294	0.60	0.60	6023	6023
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		400	
	non noble metal	copper	7440-50-8	815.335	39.95	40.00	399482	400002
	non noble metal	aluminium	7429-90-5	7.941	0.39	0.39	3891	3891
wire	non noble metal	aluminium	7429-90-5	7.941	0.39	0.39	3891	3891
encapsulation	organic material	carbon black	1333-86-4	8.769	0.43		4297	
	plastics	epoxy resin	-	96.464	4.73		47264	
	inorganic material	silicondioxide	60676-86-0	479.397	23.49	28.65	234886	286447
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10516	10516
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.155	0.01		76	
	noble metal	silver	7440-22-4	0.194	0.01		95	
	non noble metal	lead	7439-92-1	7.423	0.36	0.38	3637	3808
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		289	
	non noble metal	copper	7440-50-8	589.466	28.88	28.92	288816	289192
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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